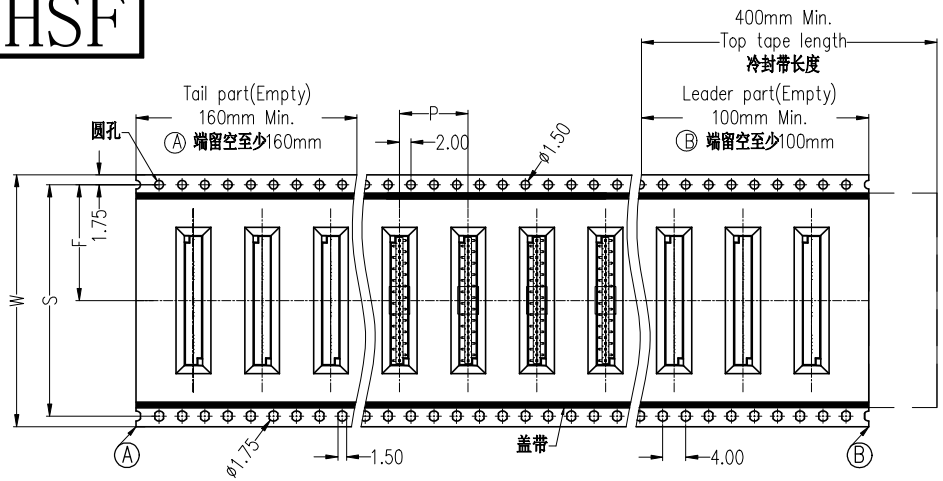
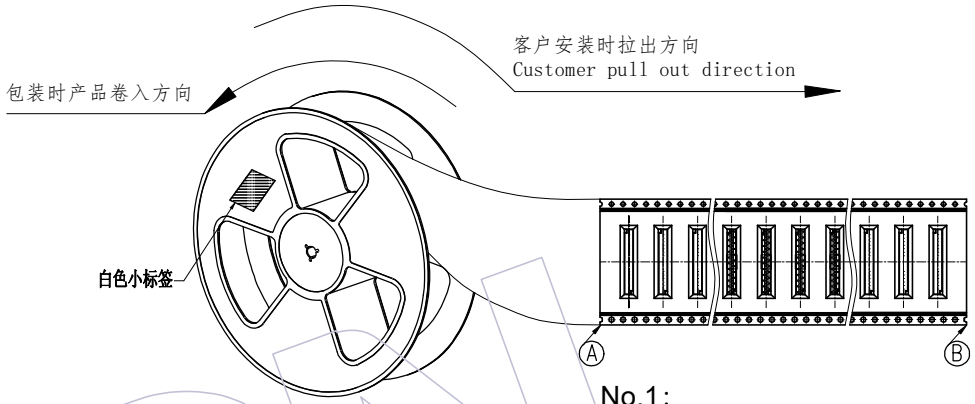
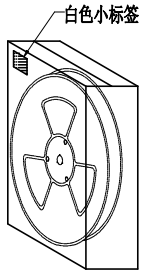
HSF



剖视图

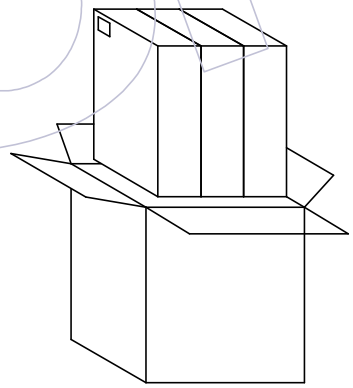


No.1:
产品包装前,注意载带要留空160mm以上
将产品放入载带凹槽后,用盖带封装,
注意:盖带与承载带的拉力30g-120g

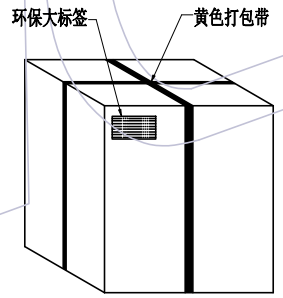


内箱：CTN-18E

No.2:
将卷盘套上防水袋,
放入1包干燥剂,
真空机封口后装入内箱,
用封箱胶封装好,并贴上标签。



No.3:
将内箱装入外箱(3内箱/外箱)
注意统一标签方向



外箱：CTN-18K

No.4:
封箱,打包,贴标签。

说明
1. 产品如图所示型态放入载带
2. 注意各标签样式.位置及方向的一致性;
3. 标签如客户有特殊要求，则按客户要求黏贴;
4. 打外箱包装带时需注意，打为十字型,另出国内客户，未打包装带。
5. 未尽事宜依据交货注意事项。

W	S	F	Reel/内箱	内箱/外箱
12.0±0.30	\	5.50±0.15	6	3
16.0±0.30	\	7.50±0.15	4	3
24.0±0.30	\	11.50±0.15	3	3
32.0±0.30	28.40±0.15	14.20±0.15	2	3
44.0±0.30	40.40±0.15	20.20±0.15	2	3
56.0±0.30	52.40±0.15	26.20±0.15	1	3
72.0±0.30	68.40±0.15	34.20±0.15	1	3
88.0±0.30	84.40±0.15	42.20±0.15	1	3
104.0±0.30	100.40±0.15	50.20±0.15	1	3

变更记事												
					工程图 ENGINEERING		绘图 DRAW	苏珊	2023/03/15	SCALE	FIT	WCON
					X.X	±0.30	设计 DESIGN			UNIT	mm	WCON ELECTRONICS (GUANGDONG) CO.,LTD
					X.XX	±0.20				SIZE	A4	料号 PART NO. WF2005-WSXXET1
A0	2023/03/15	NEW	------	------	X.XXX	±0.10	审核 CHECK			SHEET	1/1	
					Angle	± 2°	核准 APPROVE			PROJ.		品名 TITLE: 2.00mm Wafer,Vertical DIP包装规范
版次 REV	日期 DATE	变更说明 MODIFICATION DESCRIPTION	变更 CHANGE	核准 APPROVE	DIM	TOL						